Product/process change notification

PCN220201

Please find attached our Infineon Technologies AG PCN:

Change of die attach from DF-18C1 to EM760 for select MCU products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **24 Feb 2022**
- Infineon aligns with the widely-recognized JEDEC STANDARD **"JESD46",** which stipulates:
  "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Products affected:

Please refer to attached affected product list [2]

Detailed change information:

Subject: Change of die attach from DF-18C1 to EM760 for select 121-ball FBGA package products assembled at Amkor Technology Japan, Inc. Hakodate, Japan

Reason: To further improve/ensure our product performance the new die attach will be introduced.

Description:

Old	New
■ Die attach material DF-18C1	■ Die attach material EM760

Product identification:

Traceability of product to assembly site through the lot number marked on the package.

Impact of change:

Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form.

Attachments:

Affected product list [2]
Supporting documents

Time schedule:

■ Final qualification report:	2021-09-06
■ First samples available:	on request
■ Intended start of delivery:	2022-04-15

If you have any questions, please do not hesitate to contact your local sales office.

[Product Change Notification] N° [PCN220201]

Change of die attach from DF-18C1 to EM760 for select MCU products

Item	Marketing Part Number	Family	Sample Order Part Number	Sample Availability
1	S6E2H14G0AGB3000A	MM MCU	S6E2H14G0AGB3000Z	on request
2	S6E2H16G0AGB3000A	MM MCU	S6E2H16G0AGB3000Z	on request